

Thin Film Receiver Materials for Deterministic Assembly by Transfer Printing

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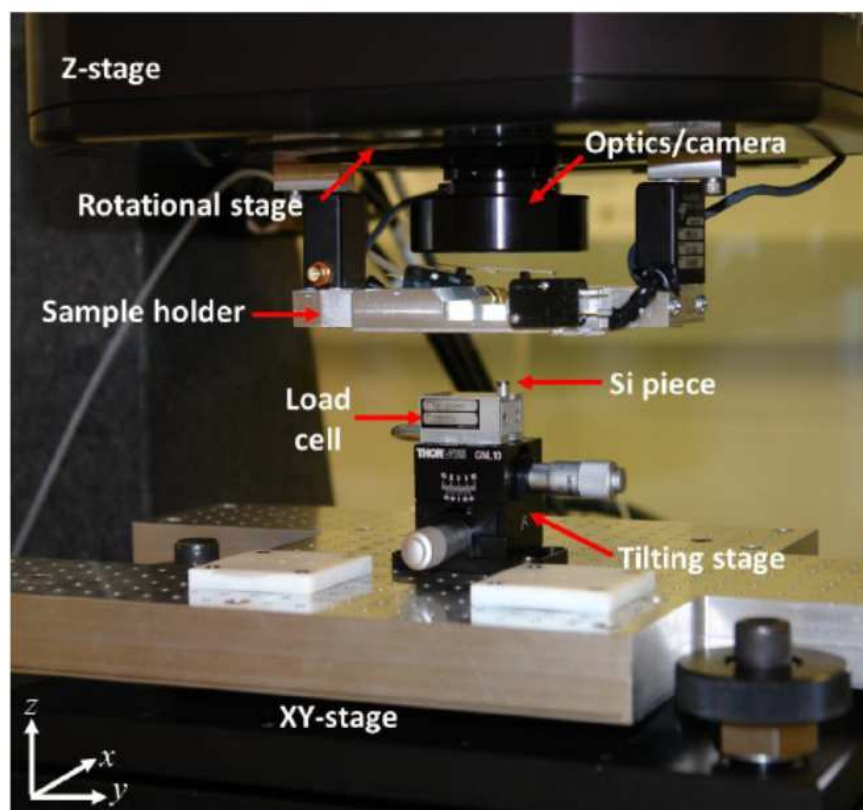


Figure SI1. Image for stage of adhesion force measurement.

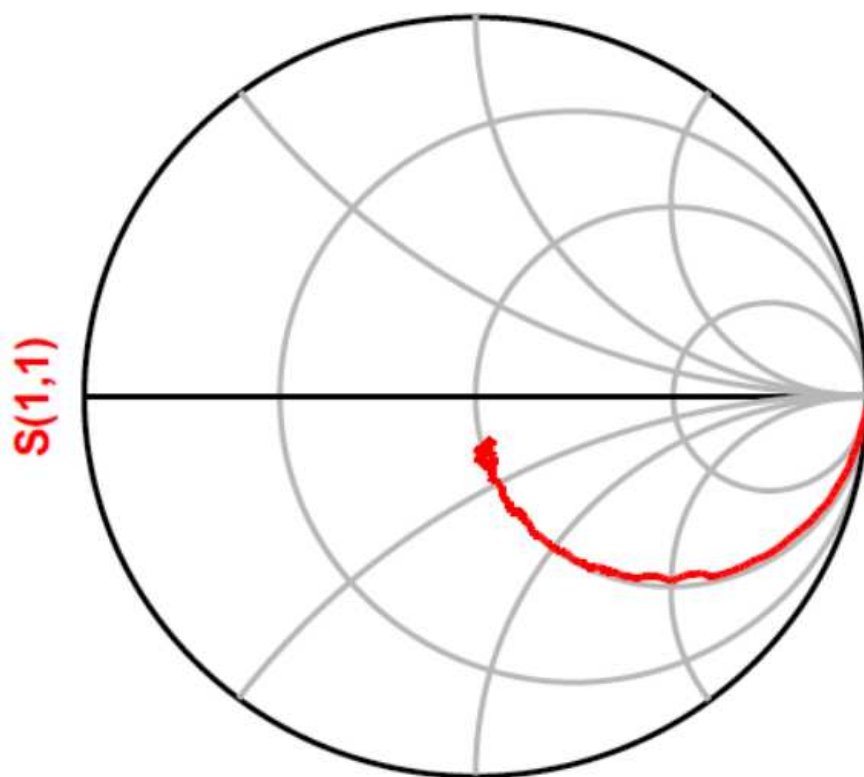


Figure SI2. Measured S_{11} result of the MIM capacitor on a Smith chart from 100 MHz to 20 GHz